

Paragraph beginning on page 17, line 1 has been amended as follows:

A11  
--The insulators (spacers) 12 have cavities for accommodating the end portions of the semiconductor chips 7, and are stacked so that the conductive patterns 11 of the insulators (spacers) 12 adjacent to each other are placed so as to be electrically connected to each other.--

**IN THE CLAIMS**

Please cancel claims 1, 2, 5, 7, 10, and 11 without prejudice or disclaimer.

Please amend claims 3, 4, 6, 8, 9, 12, 13, and 15 to read as follows:

3. A semiconductor device comprising:

a semiconductor chip;

at least a first electrode formed on the first major surface of said semiconductor chip,

at least a second electrode or an insulation layer formed on the second major surface opposite to said first major surface; and

A12  
at least a conductive member for connecting said first electrode with said second electrode or said insulation layer, said conductive member being formed along the outer circumference of at least a side of said semiconductor chip,

wherein each of said conductive members is comprised of a conductive clip holding said first electrode together with said second electrode or said insulation layer, said conductive clip having elasticity for clamping objects.

4. A semiconductor device comprising:

a semiconductor chip;

at least a first electrode formed on the first major surface of said semiconductor chip,

at least a second electrode or an insulation layer formed on the second major surface opposite to said first major surface; and

at least a conductive member for connecting said first electrode with said second electrode or said insulation layer, said conductive member being formed along the outer circumference of at least a side of said semiconductor chip,

wherein each of said conductive members is comprised of a conductive layer formed on the surface of said semiconductor chip extending from said first electrode to said second electrode or said insulation layer.

6. A semiconductor device comprising:

a plurality of semiconductor device units, each of said semiconductor device units including:

a semiconductor chip;

at least a first electrode formed on the first major surface of said semiconductor chip,

at least a second electrode or an insulation layer formed on the second major surface opposite to said first major surface; and

at least a conductive member for connecting said first electrode with said second electrode or said insulation layer, said conductive member being formed along the outer circumference of at least a side of said semiconductor chip;

wherein said semiconductor device units are stacked on each other,

wherein a first chip has a first conducting pattern extended from said first electrode, a second chip has a second conducting pattern extended from said second electrodes, and a bump is provided between said first conducting pattern and said second conducting pattern, which face to each other, for electrically connecting said two conducting patterns.

cont. 8. A semiconductor device comprising:

A12 a plurality of semiconductor device units, each of said semiconductor device units

including:

mul B1 a semiconductor chip;

at least a first electrode formed on the first major surface of said semiconductor chip,

at least a second electrode or an insulation layer formed on the second major surface opposite to said first major surface; and

at least a conductive member for connecting said first electrode with said second electrode or said insulation layer, said conductive member being formed along the outer circumference of at least a side of said semiconductor chip;

wherein said semiconductor device units are stacked each other, and said conductive members are connected to each other,

wherein each of said conductive members is comprised of a conductive clip holding said first electrode together with said second electrode or said insulation layer, said conductive clip having elasticity for clamping objects.

9. A semiconductor device comprising:

a plurality of semiconductor device units, each of said semiconductor device units including:

a semiconductor chip;

at least a first electrode formed on the first major surface of said semiconductor chip,

at least a second electrode or an insulation layer formed on the second major surface opposite to said first major surface; and

at least a conductive member for connecting said first electrode with said second electrode or said insulation layer, said conductive member being formed along the outer circumference of at least a side of said semiconductor chip;

wherein said semiconductor device units are stacked each other, and said conductive members are connected to each other,

wherein each of said conductive members is comprised of a conductive layer formed on the surface of said semiconductor chip extending from said first electrode to said second electrode or said insulation layer.

12. A semiconductor device comprising:

a plurality of semiconductor device units, each of said semiconductor device units including:

a semiconductor chip;

at least a first electrode formed on the first major surface of said semiconductor chip,

at least a second electrode or an insulation layer formed on the second major surface opposite to said first major surface; and

at least a conductive member for connecting said first electrode with said second electrode or said insulation layer, said conductive member being formed along the outer circumference of at least a side of said semiconductor chip;

a packaging board for mounting said plurality of semiconductor device units;

wherein said semiconductor device units are placed on said packaging board so as to have a predetermined angle to said packaging board, and said conductive members of said semiconductor device units are connected to said packaging board,

wherein each of said conductive members is comprised of a conductive clip holding said first electrode together with said second electrode or said insulation layer, said conductive clip having elasticity for clamping objects.

13. A semiconductor device comprising:

a plurality of semiconductor device units, each of said semiconductor device units including:

a semiconductor chip;

at least a first electrode formed on the first major surface of said semiconductor chip,

at least a second electrode or an insulation layer formed on the second major surface opposite to said first major surface; and

at least a conductive member for connecting said first electrode with said second electrode or said insulation layer, said conductive member being formed along the outer circumference of at least a side of said semiconductor chip;

a packaging board for mounting said plurality of semiconductor device units;

wherein said semiconductor device units are placed on said packaging board so as to have a predetermined angle to said packaging board, and said conductive members of said semiconductor device units are connected to said packaging board,

wherein each of said conductive members is comprised of conductive layer formed on the surface of said semiconductor chip extending from said first electrode to said second electrode or said insulation layer.

15. The semiconductor device according to claim 14, wherein each of said spacer members has a cavity for accommodating the end portion of said semiconductor chip, said end portion is located at least partially within the cavity.

#### REMARKS

In order to expedite prosecution, independent claims 1, 5 and 10 and dependent claims 2, 7 and 11 have been canceled. Claims 3, 4, 6, 8, 9, 12 and 13 have been